Thermomechanical Fatigue of Solders

CORE :

Thermomechanical Fatigue in Solder Materials

D. R. Frear, Solder Mechanics – State of the Art Assessment, D.R. Frear, W. B. Jones and K. R. Kinsman, eds., TMS, Warrendale, PA, 1990, pp.191-237.

RECENT PROGRESS:

Thermomechanical Fatigue and Fracture of Sn-based Solders

K.N. Subramanian and A. Lee, 2006 TMS State of the Art Lead-Free Solder Technology Workshop, TMS 2006 Annual Meeting.

The Orientation Imaging Microscopy of Lead-Free Sn-Ag Solder Joints

A.U. Telang and T.R. Bieler, JOM, June 2005, pp. 44-49.

WEB RESOURCE:

Fatigue Life Correlations

National Institute of Standards, 2004.

Test Procedures for Developing Solder Data

T. A. Siewart and C. A. Handwerker, National Institute of Standards, 2002.

Experiments Needed to Characterize Solder Joint Behavior

A. Zubelewicz, Modeling and Data Needs for Lead-Free Solders,iNEMI, 2001.